

ABSTRACT

An electronic component attaching tool suitable for an external shape of a semiconductor device is prepared. The electronic component
5 attaching tool has a function of aligning a position of the semiconductor device to an IC socket. The electronic component attaching tool is mounted on the standard surface that is formed on the IC socket substantially regardless of the external shape of
10 the semiconductor device. The semiconductor device is then aligned and attached to the IC socket by using the electronic component attaching tool, and the electronic component attaching tool is removed from the IC socket. Another electronic component
15 attaching tool suitable for an external shape of another semiconductor device is prepared, and the same procedure as the above is performed to align and attach this semiconductor device to the same type IC socket.

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